



DSS3515M

15V LOW V_{CE(sat)} PNP SURFACE MOUNT TRANSISTOR

Features

- Low Collector-Emitter Saturation Voltage, V_{CE(sat)}
- Ultra-Small Leadless Surface Mount Package
- ESD: HBM 8kV, MM 400V
- Complementary NPN Type Available (DSS2515M)
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)

Mechanical Data

- Case: DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0009 grams (Approximate)

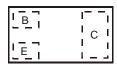
DFN1006-3







Device Symbol



Top View Device Schematic

Ordering Information (Note 3)

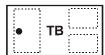
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DSS3515M-7	ТВ	7	8	3,000
DSS3515M-7B	ТВ	7	8	10,000

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com.

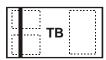
Marking Information

DSS3515M-7



Top View Dot Denotes Collector Side

DSS3515M-7B



Top View Bar Denotes Base and Emitter Side

TB = Product Type Marking Code



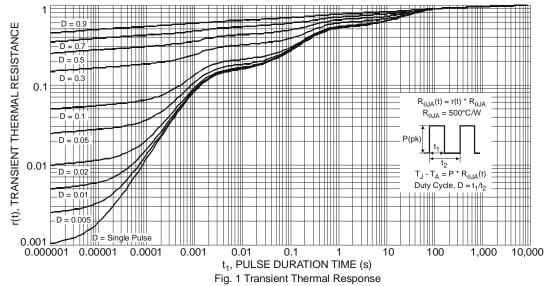
Maximum Ratings @TA = 25°C unless otherwise specified

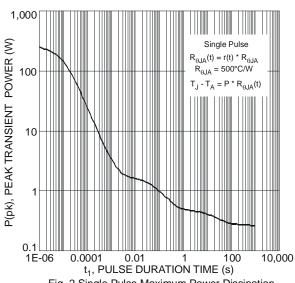
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-15	V
Collector-Emitter Voltage	V_{CEO}	-15	V
Emitter-Base Voltage	V _{EBO}	-6	V
Collector Current - Continuous	Ic	-500	mA
Peak Pulse Collector Current	I _{CM}	-1	А
Peak Base Current	I _{BM}	-100	mA

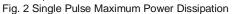
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4) @ T _A = 25°C	PD	250	mW
Thermal Resistance, Junction to Ambient (Note 4) @ T _A = 25°C	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

4. Device mounted on FR-4 PCB with minimum recommended pad layout. Notes:







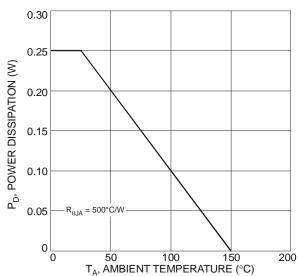


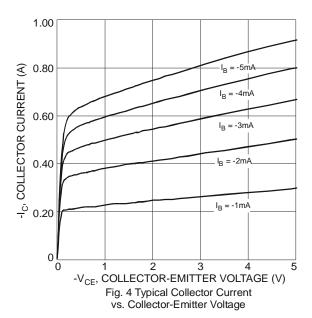
Fig. 3 Power Dissipation vs. Ambient Temperature (Note 4)

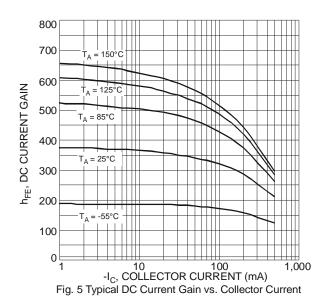


Electrical Characteristics @T_A = 25°C unless otherwise specified

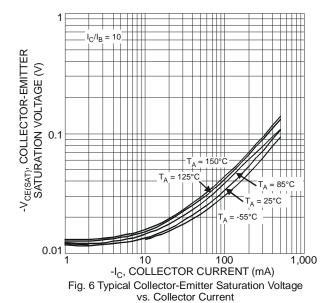
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-15			٧	$I_C = -100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 5)	BV _{CEO}	-15			٧	$I_C = -10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{)EBO}	-6			V	$I_E = -100 \mu A, I_C = 0$
Collector Cutoff Current	1			-100	nA	$V_{CB} = -15V, I_E = 0$
Collector Cutoff Current	I _{CBO}			-50	μΑ	$V_{CB} = -15V$, $I_E = 0$, $T_A = 150$ °C
Emitter Cutoff Current	I _{EBO}	_	_	-100	nA	$V_{EB} = -5V, I_C = 0$
ON CHARACTERISTICS (Note 5)						
		200	_	_		$V_{CE} = -2V, I_{C} = -10mA$
DC Current Gain	h _{FE}	150	_	_	_	$V_{CE} = -2V, I_{C} = -100mA$
		90	_			$V_{CE} = -2V, I_{C} = -500mA$
		_	_	-25		$I_C = -10 \text{mA}, I_B = -0.5 \text{mA}$
Collector-Emitter Saturation Voltage	V _{CE(sat)}	_	_	-150	mV	$I_C = -200 \text{mA}, I_B = -10 \text{mA}$
		_	_	-250		$I_C = -500 \text{mA}, I_B = -50 \text{mA}$
Collector-Emitter Saturation Resistance	R _{CE(sat)}	_	_	500	mΩ	$I_C = -500 \text{mA}, I_B = -50 \text{mA}$
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	_	-1.1	V	$I_C = -500 \text{mA}, I_B = -50 \text{mA}$
Base-Emitter Turn On Voltage	V _{BE(on)}	_	_	-0.9	V	$V_{CE} = -2V, I_{C} = -100mA$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}		_	10	pF	$V_{CB} = -10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f _T	100	340	_	MHz	V _{CE} = -5V, I _C = -100mA, f = 100MHz

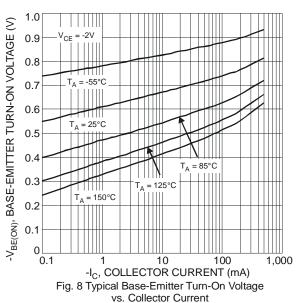
Notes: 5. Measured under pulsed conditions. Pulse width = 300μ s. Duty cycle $\leq 2\%$.











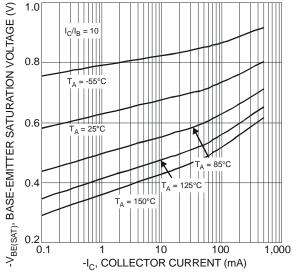
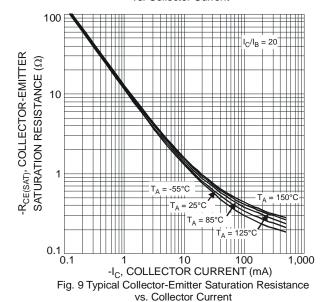
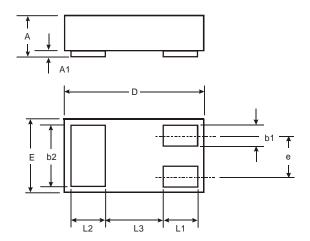


Fig. 7 Typical Base-Emitter Saturation Voltage
vs. Collector Current



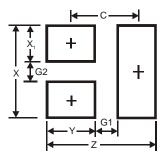
Package Outline Dimensions



DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b1	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е		_	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3		_	0.40		
All Dimensions in mm					



Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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